



Features

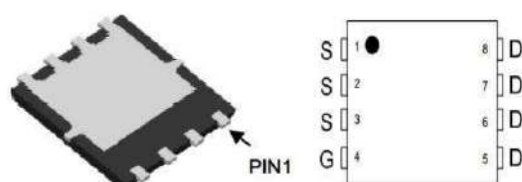
- ◇ High Speed Power Switching, Logic Level
- ◇ Enhanced Body diode dv/dt capability
- ◇ Enhanced Avalanche Ruggedness
- ◇ 100% UIS Tested, 100% Rg Tested
- ◇ Lead Free, Halogen Free

Application

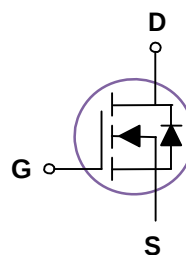
- ◇ Synchronous Rectification in SMPS
- ◇ Hard Switching and High Speed Circuit
- ◇ DC/DC in Telecoms and Industrial

Product Summary

V_{DS}	100	V
$R_{DS(on), Typ @ V_{GS}=10V}$	7.3	mΩ
I_D	55	A



DFN5×6-8



Absolute Maximum Ratings at $T_J=25^{\circ}\text{C}$ (unless otherwise specified)

Parameter	Symbol	Conditions	Value	Unit
Continuous Drain Current (Silicon Limited)	I_D	$T_C=25^{\circ}\text{C}$	55	A
		$T_C=100^{\circ}\text{C}$	38	
Drain to Source Voltage	V_{DS}	-	100	V
Gate to Source Voltage	V_{GS}	-	+20/-12	V
Pulsed Drain Current	I_{DM}	-	80	A
Avalanche Energy, Single Pulse	E_{AS}	$L=0.1\text{mH}, T_C=25^{\circ}\text{C}$	80	mJ
Power Dissipation	P_D	$T_C=25^{\circ}\text{C}$	3.1	W
Operating and Storage Temperature	T_J, T_{stg}	-	-55 to 150	$^{\circ}\text{C}$

Absolute Maximum Ratings

Parameter	Symbol	Max	Unit
Thermal Resistance Junction-Lead	$R_{\theta JL}$	23	$^{\circ}\text{C/W}$
Thermal Resistance Junction-Ambient ($t \leq 10\text{s}$)	$R_{\theta JA}$	40	$^{\circ}\text{C/W}$
Thermal Resistance Junction-Ambient (steady state)		75	$^{\circ}\text{C/W}$

Electrical Characteristics at $T_j=25^{\circ}\text{C}$ (unless otherwise specified)

Static Characteristics						
Parameter	Symbol	Conditions	Value			Unit
			min	typ	max	
Drain to Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	100	-	-	V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	1	1.8	2.5	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{GS}=0V, V_{DS}=95V, T_J=25^{\circ}C$	-	-	1	μA
		$V_{GS}=0V, V_{DS}=95V, T_J=125^{\circ}C$	-	-	100	
Gate to Source Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	± 100	nA
Drain to Source on Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=14A$	-	7.3	9	m Ω
		$V_{GS}=4.5V, I_D=10A$	-	11	12	
Transconductance	g_{fs}	$V_{DS}=5V, I_D=14A$	-	70	-	S
Gate Resistance	R_G	$V_{GS}=0V, V_{DS}$ Open, $f=1MHz$	-	1.5	-	Ω
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{GS}=0V, V_{DS}=50V, f=1MHz$	-	3350	-	pF
Output Capacitance	C_{oss}		-	270	-	
Reverse Transfer Capacitance	C_{rss}		-	15	-	
Total Gate Charge	$Q_g(10V)$	$V_{DD}=50V, I_D=14A, V_{GS}=10V$	-	49	-	nC
Total Gate Charge	$Q_g(4.5V)$		-	21	-	
Gate to Source Charge	Q_{gs}		-	8	-	
Gate to Drain (Miller) Charge	Q_{gd}		-	7	-	
Turn on Delay Time	$t_{d(on)}$	$V_{DD}=50V, I_D=14A, V_{GS}=10V, R_G=10\Omega,$	-	10	-	ns
Rise time	t_r		-	5	-	
Turn off Delay Time	$t_{d(off)}$		-	32	-	
Fall Time	t_f		-	6	-	
Reverse Diode Characteristics						
Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_F=14A$	-	0.9	1.2	V
Reverse Recovery Time	t_{rr}	$V_R=50V, I_F=14A, dI_F/dt=500A/\mu s$	-	47	-	ns
Reverse Recovery Charge	Q_{rr}		-	226	-	nC

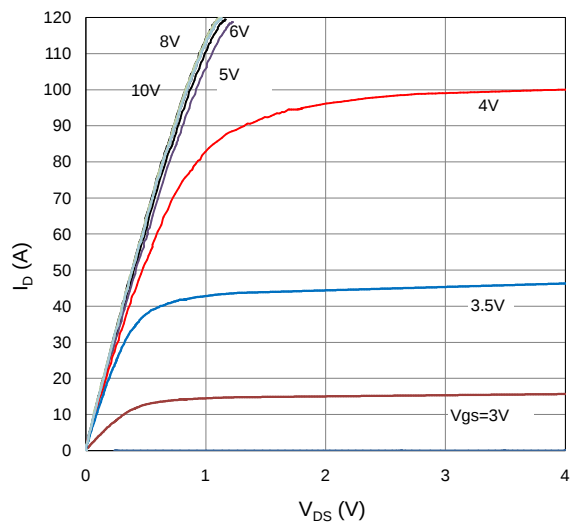
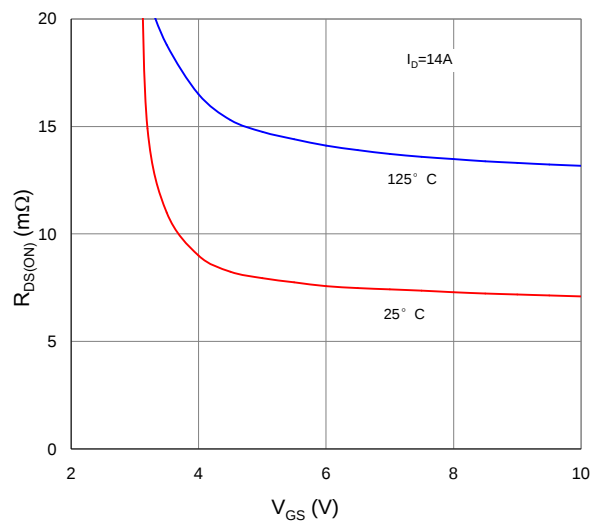
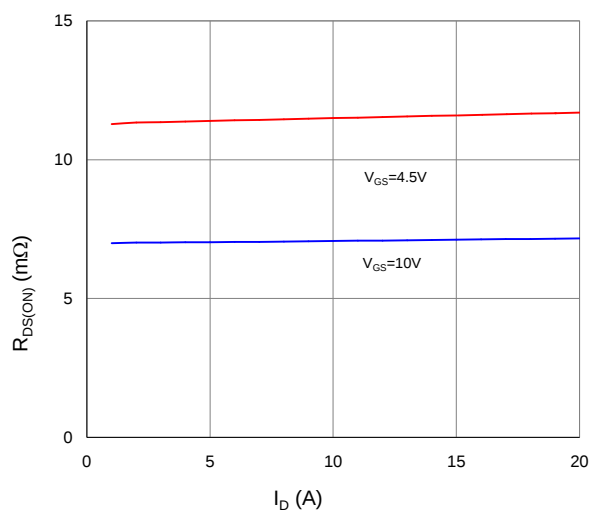
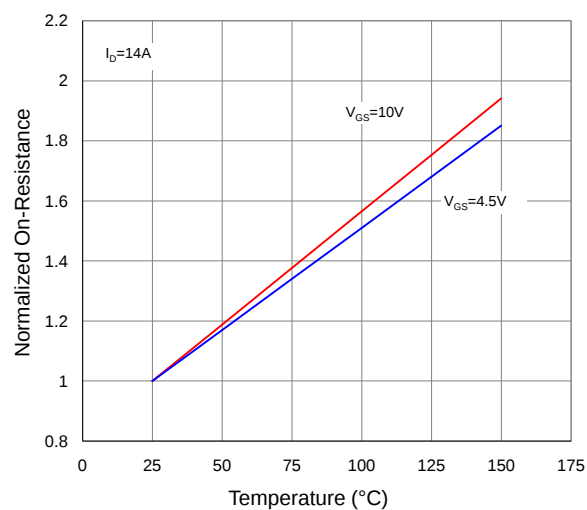
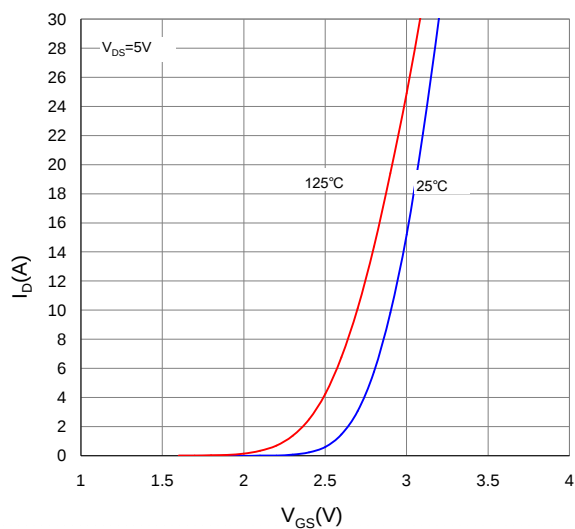
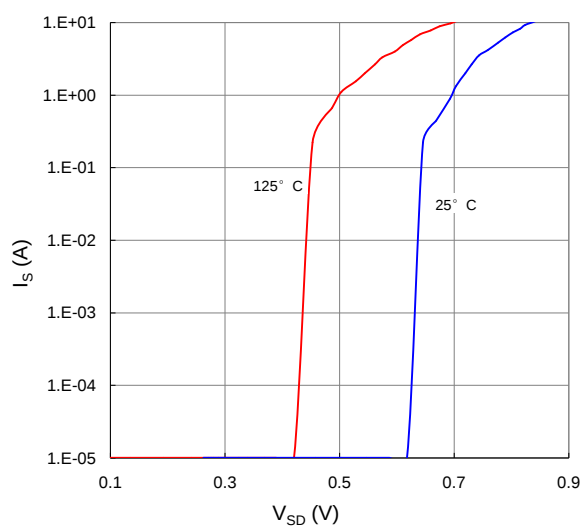
Fig 1. Typical Output Characteristics

Figure 2. On-Resistance vs. Gate-Source Voltage

Figure 3. On-Resistance vs. Drain Current and Gate Voltage

Figure 4. Normalized On-Resistance vs. Junction Temperature

Figure 5. Typical Transfer Characteristics

Figure 6. Typical Source-Drain Diode Forward Voltage


Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

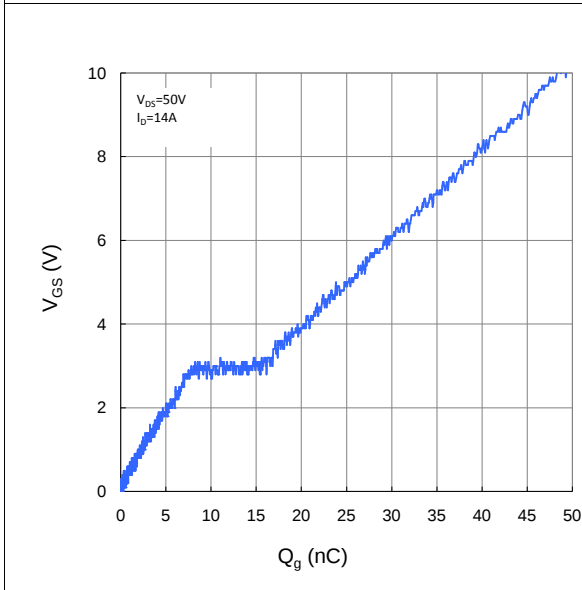


Figure 8. Typical Capacitance vs. Drain-to-Source Voltage

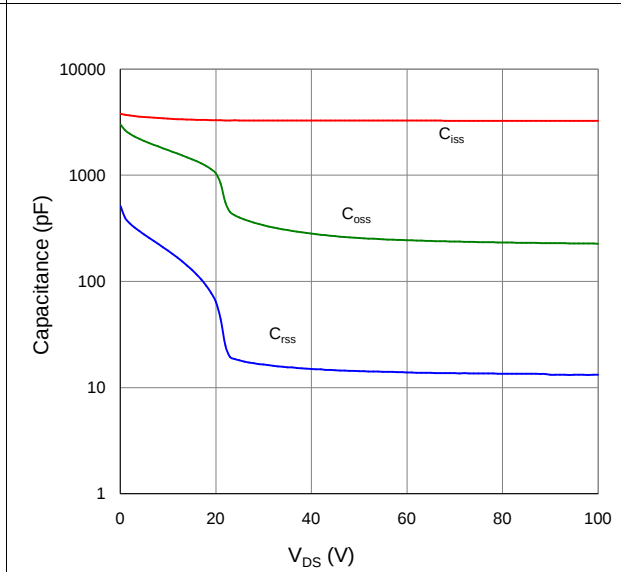


Figure 9. Maximum Safe Operating Area

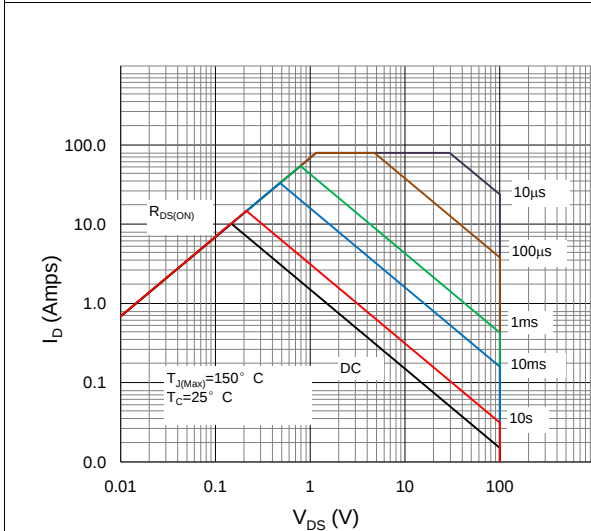


Figure 10. Maximum Drain Current vs. Case Temperature

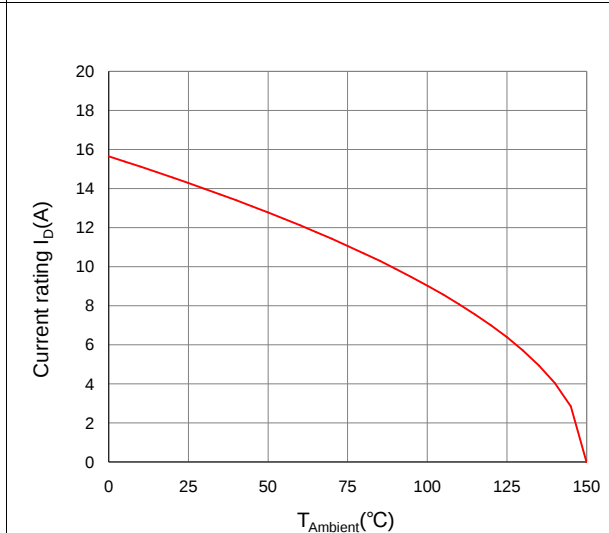
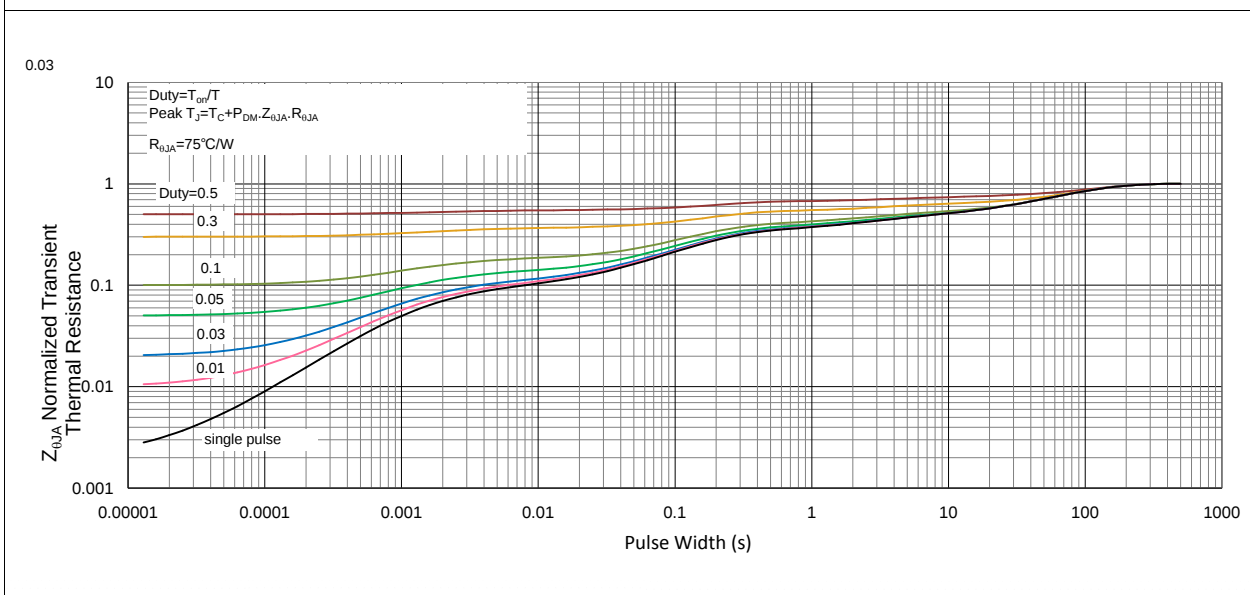
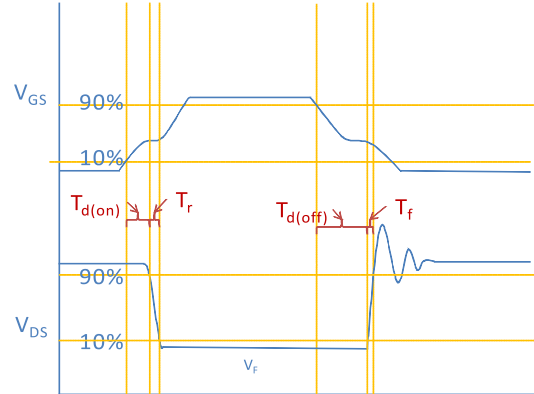
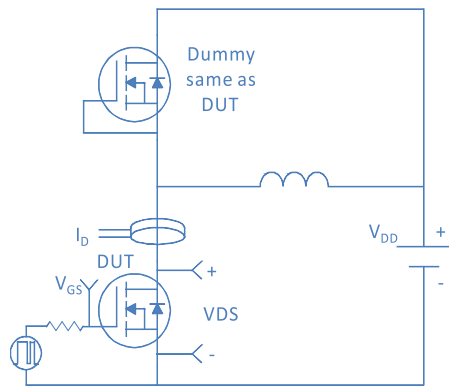


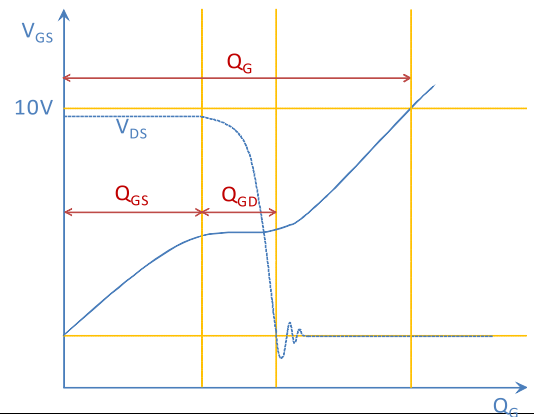
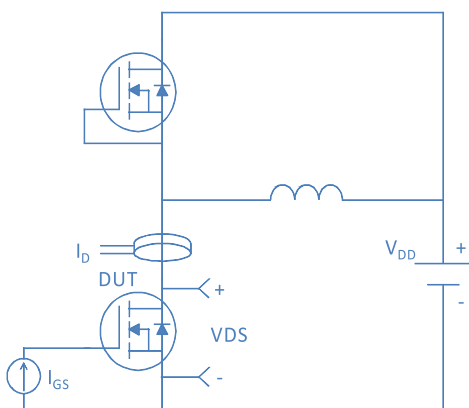
Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Ambient



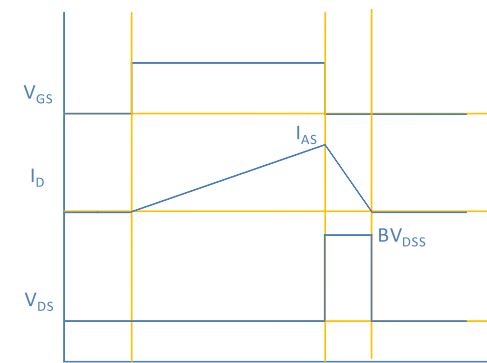
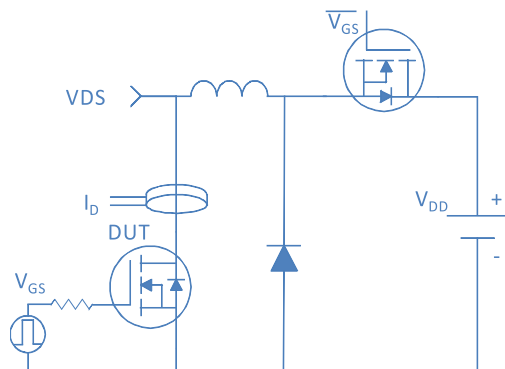
Inductive switching Test



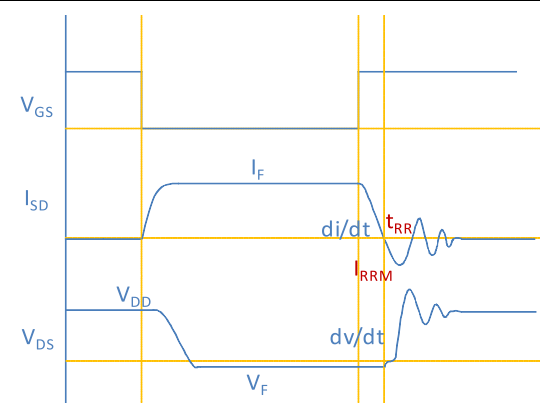
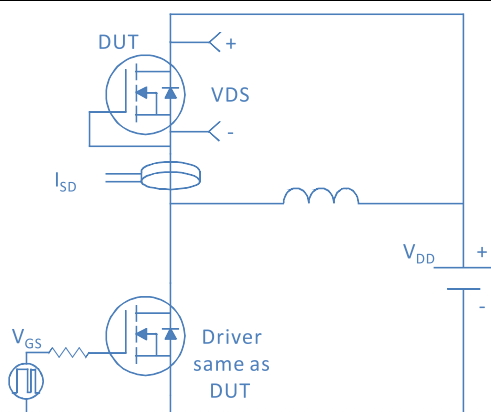
Gate Charge Test



Uclamped Inductive Switching (UIS) Test

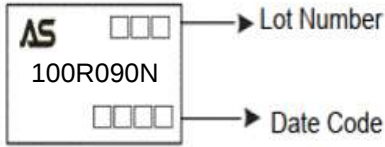


Diode Recovery Test

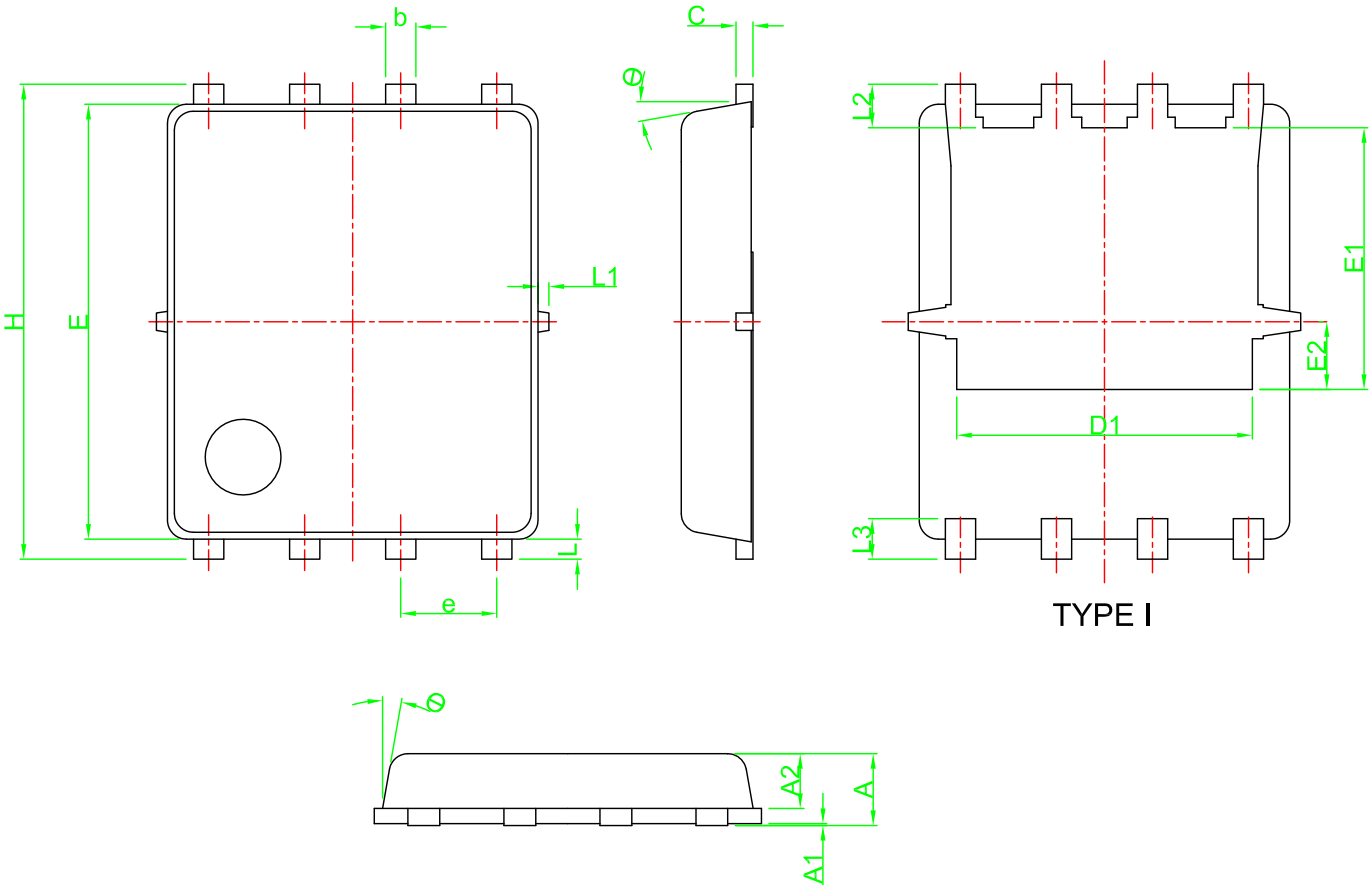


Ordering and Marking Information

Ordering Device No.	Marking	Package	Packing	Quantity
ASDM100R090NQ-R	100R090N	DFN5*6-8	Tape&Reel	4000/Reel

PACKAGE	MARKING
DFN5*6-8	 AS □□□ → Lot Number 100R090N □□□□ → Date Code

DFN5*6-8 PACKAGE IN FORMATION



Symbol	Dimensions in Millimeters		Dimensions in Inches	
	Min	Max	Min	Max
A	0.85	1.00	0.033	0.039
A1	0.01	0.05	0.000	0.002
A2	0.69	0.75	0.027	0.030
b	0.40	0.45	0.016	0.018
C	0.20	0.30	0.008	0.012
D	4.80	4.95	0.189	0.195
D1	3.91	4.06	0.154	0.160
e	1.27 TYP		0.05 TYP	
E	5.65	5.80	0.222	0.228
E1	3.46	3.50	0.136	0.138
E2	0.80	0.95	0.031	0.037
L	0.15	0.3	0.006	0.012
L1	0.08	0.15	0.003	0.006
L2	0.58	0.73	0.023	0.029
L3	0.45	0.60	0.018	0.024
H	6.15	6.28	0.242	0.247
Θ	8°	12°	8°	12°

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